

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
YOUKO MURATA	08/19/2016
YUSUKE HORIGUCHI	08/08/2016
<b>RECEIVING PARTY DATA</b>	
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<b>Street Address:</b>	2-2-8 HIGASHI SHINAGAWA
<b>City:</b>	SHINAGAWA-KU, TOKYO
<b>State/Country:</b>	JAPAN
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	15945772
<b>CORRESPONDENCE DATA</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	PT031907
<b>NAME OF SUBMITTER:</b>	JOANNE GUTIERREZ
<b>SIGNATURE:</b>	/JOANNE GUTIERREZ/
<b>DATE SIGNED:</b>	01/17/2019
<b>Total Attachments: 4</b>	
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source=PT031907_SIGNED_Assignment3_HenkelJP#page2.tif	
source=PT031907_SIGNED_Assignment3_HenkelJP#page3.tif	
source=PT031907_SIGNED_Assignment3_HenkelJP#page4.tif	

# ASSIGNMENT

**WHEREAS:**

*NAME(S) AND  
ADDRESS(ES)  
OF INVENTOR(S)  
(NAME OF ASSIGNOR(S))*

**Youko MURATA**  
Namiki 2-3-2-201, Kanazawa-ku  
Yokohama City 236-0005  
Japan  
Citizenship: Japan

**Yusuke HORIGUCHI**  
27-7 Shin Isogo-cho, Isogo-ku  
Yokohama 235-0017  
Japan  
Citizenship: Japan

(hereinafter referred to as ASSIGNOR), has/have invented a certain invention entitled:

*TITLE OF INVENTION*

**FORMULATIONS CONTAINING MIXED RESIN SYSTEMS AD  
THE USE THEREOF FOR WAFER-UNDERFILL FOR 3D TSV  
PACKAGES**

for which a patent application was filed on November 2, 2011 as U.S. Patent Application No. 61/554,698 (and I hereby authorize my attorneys authorized to prosecute said application to above insert the filing date and serial number of said application, when it is known); and

**WHEREAS:**

*FULL NAME  
AND ADDRESS  
OF ASSIGNEE*

**HENKEL JAPAN LIMITED**  
2-2-8 Higashi Shinagawa  
Shinagawa-ku, Tokyo  
Japan

(hereinafter referred to as ASSIGNEE), is desirous of acquiring the entire right, title and interest in, to and under said invention, and in, to and under the patent application in the United States and around the World,

# ASSIGNMENT

Attorney Docket No. PT031907

## **NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN:**

Be it known that for and in consideration of the payment by ASSIGNEE to ASSIGNOR of good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR, to the extent he or she has not already done so, hereby sells, assigns and transfers to ASSIGNEE the full and exclusive right, title and interest in, to and under said invention and said patent application in the United States and around the World including all priority rights related thereto and any Letters Patent obtained therefrom, together with all continuation, divisional, renewal, substitute, reissue or other patent applications that have been or may be filed on said invention.

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

ASSIGNOR further covenants and agrees that upon the request of ASSIGNEE and with no further consideration but at the expense of ASSIGNEE, ASSIGNOR will: promptly provide to ASSIGNEE all facts and documents relating to said invention or said patent application that are known or accessible to ASSIGNOR; testify in any interference, litigation or other proceeding relating to said invention or said patent application; and promptly execute and deliver to ASSIGNEE any and all papers, instruments or affidavits which may be necessary or desirable to apply for, obtain, maintain, issue or enforce patent protection for said invention or to vest title to said invention in ASSIGNEE.

**IN WITNESS WHEREOF**, I have hereunto set hand and seal:

# ASSIGNMENT

Attorney Docket No. PT031907

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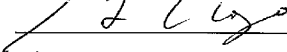
this 19 day of August, 2016.

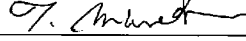
Youko MURATA  
(Typed Name of the Inventor)

  
Signature of the Inventor

1<sup>st</sup> Witness:

2<sup>nd</sup> Witness:

Signature:   
Printed Name: Hirotaki Kojo

Signature:   
Printed Name: Tsutomu Mineoka

\*\*\*\*\*

this \_\_\_\_\_ day of \_\_\_\_\_, 2016.

Yusuke HORIGUCHI  
(Typed Name of the Inventor)

\_\_\_\_\_  
Signature of the Inventor

1<sup>st</sup> Witness:

2<sup>nd</sup> Witness:

Signature: \_\_\_\_\_  
Printed Name: \_\_\_\_\_

Signature: \_\_\_\_\_  
Printed Name: \_\_\_\_\_

\*\*\*\*\*

# ASSIGNMENT

Attorney Docket No. PT031907

\*\*\*\*\*

this \_\_\_\_\_ day of \_\_\_\_\_, 2016.

**Youko MURATA**

(Typed Name of the Inventor)

\_\_\_\_\_  
Signature of the Inventor

1<sup>st</sup> Witness:

2<sup>nd</sup> Witness:

Signature: \_\_\_\_\_

Signature: \_\_\_\_\_

Printed  
Name:

Printed Name

\*\*\*\*\*

this 8th day of August, 2016.

**Yusuke HORIGUCHI**

(Typed Name of the Inventor)

Y. Horiguchi  
Signature of the Inventor

1<sup>st</sup> Witness:

2<sup>nd</sup> Witness:

Signature: Hajime Inoue

Signature: H. Ohno

Printed  
Name: Hajime Inoue

Printed Name Hiromasa Ohno

\*\*\*\*\*